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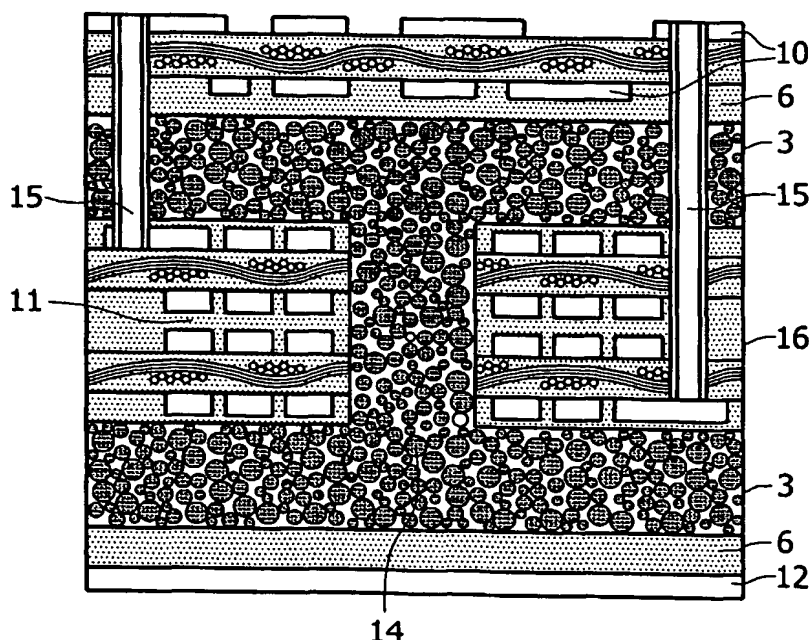
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(54) Title: **SOFT MAGNETIC MATERIAL FOR MANUFACTURING PRINTED CIRCUIT BOARDS**



(57) Abstract: The present invention relates to a soft magnetic material for use in the manufacturing of printed circuit boards. During the manufacturing of the printed magnetic circuit boards, the soft magnetic layer is used, such that it forms an integral part of the PCB after the manufacturing. In particular, the soft magnetic layers are formed such that, together with suitable circuit structures, an inductive component is formed. According to an aspect of the present invention, a polymer matrix of the soft magnetic layer is compatible to materials and/or processes used during the PCB manufacturing process.

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